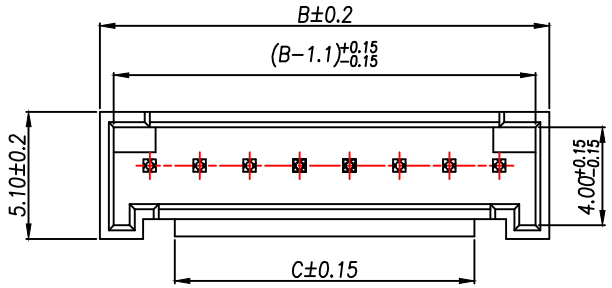
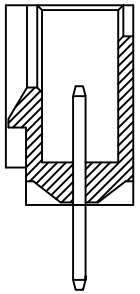
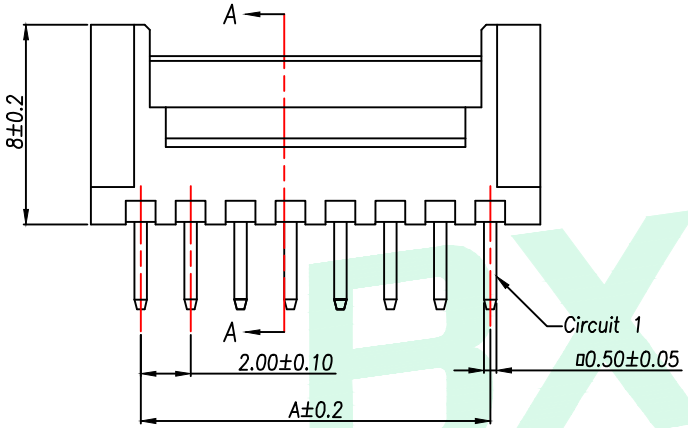
REV.	DESCRIPTION	ECN NO.	NAME	DATE

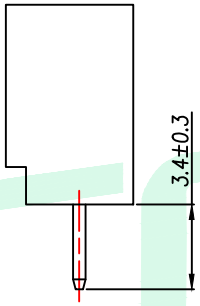




SECTION A−A

PRELIMINARY
DESIGN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE

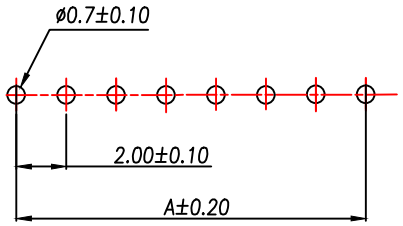




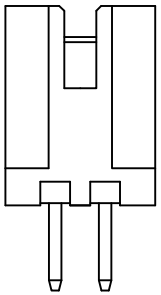
技术要求:

1、塑件材料:PA66
2、接触件:黄铜镀锡
3、接触电阻:≤10mΩ
4、绝缘电阻:≥1000MΩ
5、额定电压:250V AC DC
6、额定电流:2.0A AC DC
7、耐压:能承受1000V AC/Min ute
8、工作温度:−25°~~+85°
9、可焊性试验:浸锡面积≥95%温度220+5° −0°,时间 2.5±0.5秒
10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B	C
WF−HY2.0−2PZZ	2	2.00	6.00	3.00
WF−HY2.0−3PZZ	3	4.00	8.00	3.30
WF−HY2.0−4PZZ	4	6.00	10.00	4.00
WF−HY2.0−5PZZ	5	8.00	12.00	6.00
WF−HY2.0−6PZZ	6	10.00	14.00	8.00
WF−HY2.0−7PZZ	7	12.00	16.00	10.00
WF−HY2.0−8PZZ	8	14.00	18.00	12.00
WF−HY2.0−9PZZ	9	16.00	20.00	14.00
WF−HY2.0−10PZZ	10	18.00	22.00	16.00
WF−HY2.0−11PZZ	11	20.00	24.00	18.00
WF−HY2.0−12PZZ	12	22.00	26.00	20.00
WF−HY2.0−13PZZ	13	24.00	28.00	22.00
WF−HY2.0−14PZZ	14	26.00	30.00	24.00
WF−HY2.0−15PZZ	15	28.00	32.00	26.00



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



2P外观

序号	名 称	材 料	数 量	附 注
2	Contact	Brass	n*1	电镀(镀):整个表面镀底镍30u"MIN,再镀镍80u".MIN.
1	Wafer	PA66(UL94V−0)	1	本色

GENERAL TOLERANCE

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: WAFER 2.0mm H8.0mm 180° DIP

DWG. NO.: WF−HY2.0−XPZZ

DRAWN: MAX

PART NO.: WF−HY2.0−XPZZ

CHECKED: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED:
mm	none	1of 1	A4	bxconn	WILL